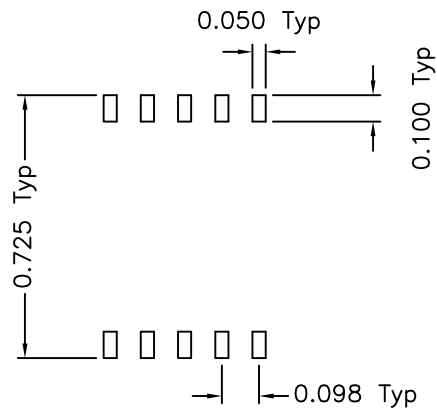
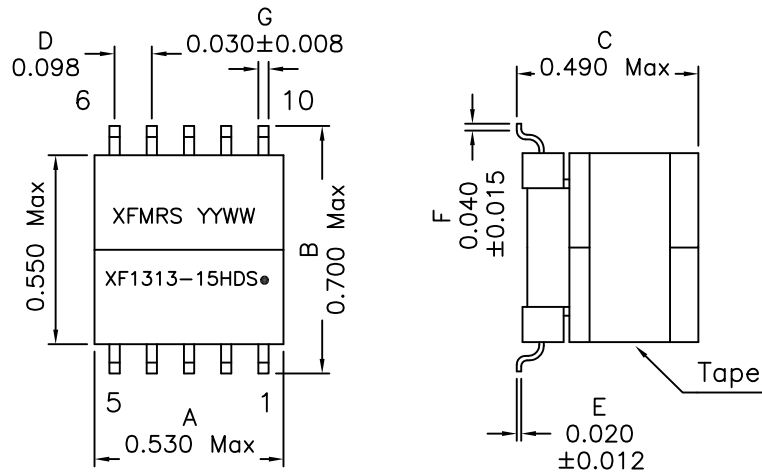


## 1. Dimensions:



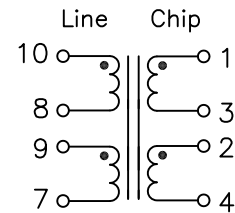
Suggested PCB Layout

### Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. All listed parameters are to be within tolerance from -40°C to +85°C unless otherwise noted.
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity:  $\pm 0.004^{\circ}$  (0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component
11. Recommended IR Reflow peak temp of 235°C Max.

DOC. REV B/3

## 2.Schematic:



## 3.Electrical Specifications: @25°C

OCL: Pins 10-7 5.0mH  $\pm 10\%$  @10KHz 0.1V 0mA DC  
(Tie 8+9)

Q: Pins 10-7 15 Min @10KHz 0.1V (Tie 8+9)

LL: Pins 10-7 14uH Max @100KHz 0.1V  
(Tie 8+9; short 1+2+3+4)

Cw/w: Pins 10-1 120pF Max @100KHz 0.1V  
(short 7+8+9+10 ; 1+2+3+4)

DCR: Pins 1-3 0.350 Ohms Max

Pins 10-8 1.75 Ohms Max

Pins 9-7 1.75 Ohms Max

Pins 2-4 0.400 Ohms Max

URNS RATIO: (10-7):(1-4) = 2.130:1  $\pm 2\%$  (Tie 8+9; 3+2)

ISOLATION VOLTAGE: 2000Vrms (Chip to Line)

SRF: Pins 10-7 50KHz Min (Tie 8+9)

UL1950 approved for the requirements of  
Supplementary Insulation with 300 working volts.  
UL file #E165866

<b>XFMRs Inc</b>  UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx $\pm 0.010$ Dimensions in INCH SHEET 1 OF 1	Title: HDSL TRANSFORMER		
	P/N: XF1313-15HDS		REV. B
	DWN.	Xiang	Apr-21-16
	CHK.	YK Liao	Apr-21-16
	APP.	DDC	Apr-21-16